

# **Reduced Inductance IC Leaded Package**

## **ABSTRACT OF THE INVENTION**

The present invention is directed a novel method and apparatus for reducing crosstalk in a lead frame based electrical device package. One cause of the crosstalk in the lead frame package is the mutual inductance between adjacent lead fingers. A conductive sheet or mesh is introduced into the lead frame package such that one edge of the conductive sheet is below the die attach pad and electrically connected to the die and another edge is below the lead fingers and electrically connected to the ground lead of the package. Such arrangement significantly reduces the inductive coupling between adjacent lead fingers by coupling the lead fingers with the conductive sheet. The conductive sheet includes an array of through holes allowing the encapsulant material from the two sides of the sheet to flow smoothly together into one body.